

ABSTRACT

Disclosed is an adhesive composition containing a thermosetting resin, a curing agent, and an elastomer, in which the thermosetting resin includes an epoxy resin having an alicyclic ring, and the elastomer includes an elastomer having a carboxy group. Furthermore, a film-form adhesive that uses such an adhesive composition is disclosed. Moreover, an adhesive sheet that uses such a film-form adhesive, and a method for producing a semiconductor device are disclosed.

No Suitable Figure